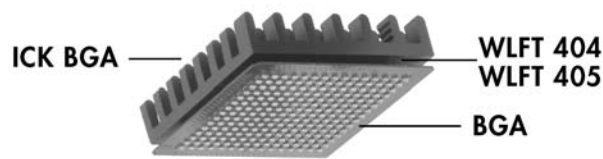
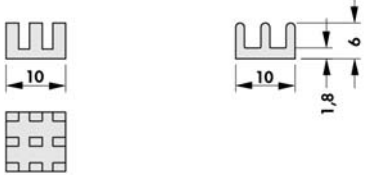
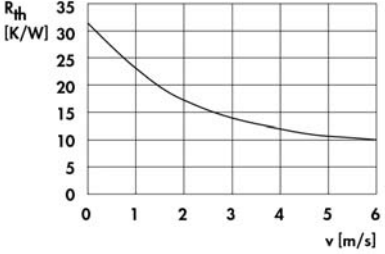

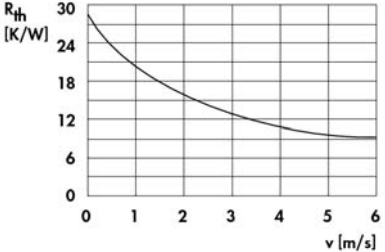
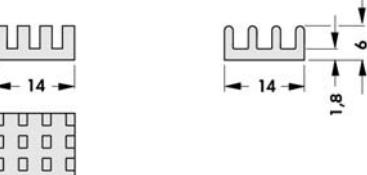
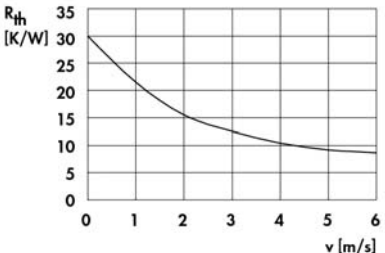
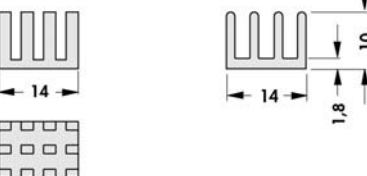
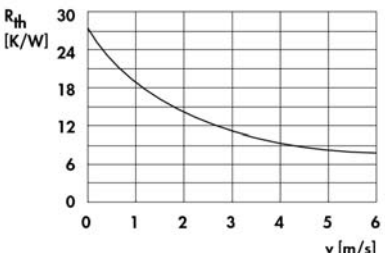
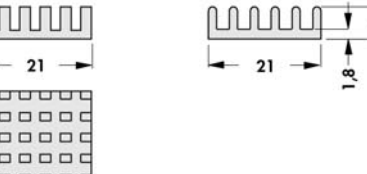
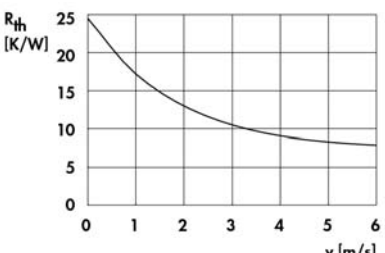


art. no.	page	$R_{th}$ [K/W]	dissipation loss [W]	mounting method	socket	suitable for processor type
<b>ICK BGA 10 x 10</b>	B 3	31.0	1.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 10 x 10 x 10</b>	B 3	28.5	1.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 14 x 14</b>	B 3	29.0	2.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 14 x 14 x 10</b>	B 3	27.4	2.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 21 x 21</b>	B 3	24.3	2.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 23 x 23</b>	B 4	22.0	2.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 23 x 23 x 10</b>	B 4	21.0	2.9	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 27 x 27</b>	B 4	20.0	3.1	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 27 x 27 x 10</b>	B 4	18.5	3.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 27 x 27 x 14</b>	B 4	13.5	9.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 27 x 27 x 22</b>	B 4	13.5	9.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 31 x 31</b>	B 5	18.6	3.4	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 31 x 31 x 10</b>	B 5	17.0	3.7	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 35 x 35</b>	B 5	16.5	3.7	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 35 x 35 x 10</b>	B 5	15.7	3.8	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 37 x 37 x 6</b>	B 5	15.7	9.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 37 x 37 x 10</b>	B 5	14.0	10.5	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 40 x 40</b>	B 6	14.3	4.3	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 40 x 40 x 10</b>	B 6	13.8	4.4	therm. conductive foil/ therm. cond. adhesive	universal	universal
<b>ICK BGA 42,5 x 45</b>	B 6	13.6	4.2	therm. conductive foil/ therm. cond. adhesive	universal	universal

## Heatsinks for BGAs



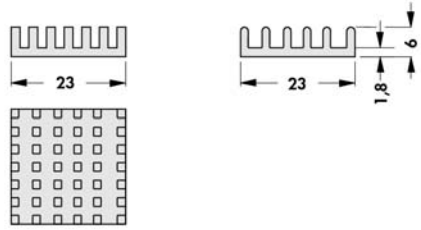
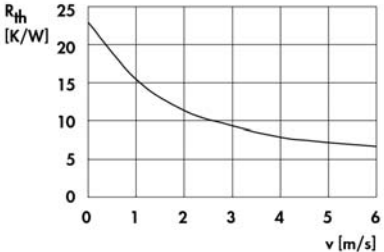
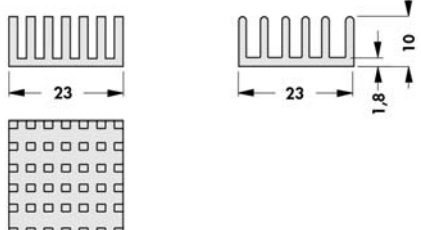
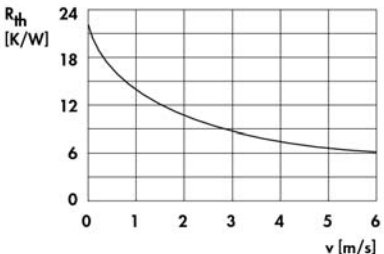
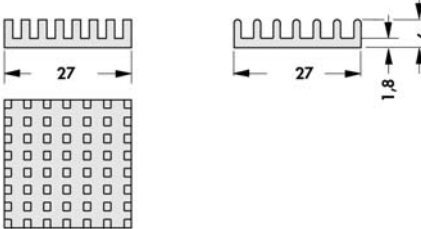
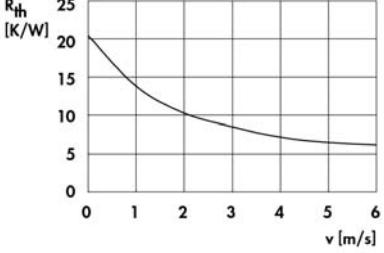
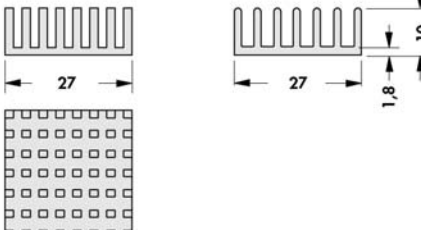
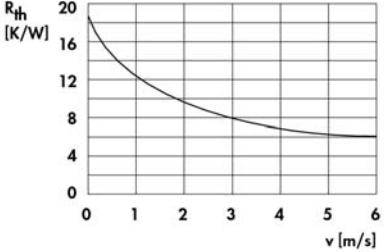
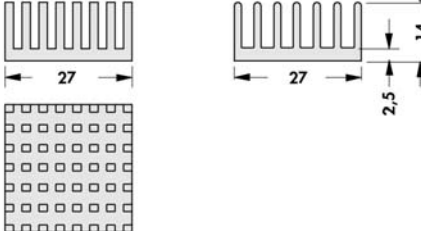
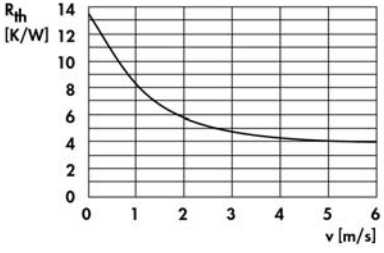
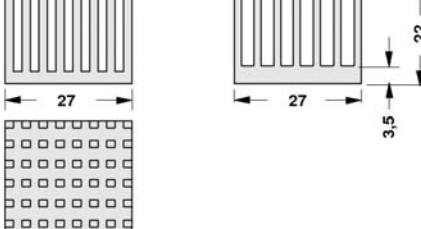
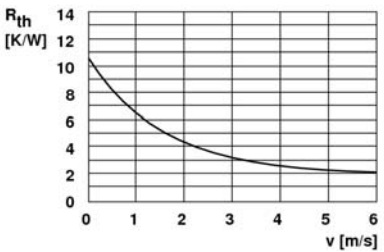
- particularly suited for **B**all **G**rid **A**rrays
- heatsink dimensions match the respective BGA-type
- can be glued directly on the BGA component

<b>art. no.</b>  <b>ICK BGA 10 x 10</b> WLF ... 10 x 10		
<b>art. no.</b>  <b>ICK BGA 10 x 10 x 10</b> WLF ... 10 x 10		
<b>art. no.</b>  <b>ICK BGA 14 x 14</b> WLF ... 14 x 14		
<b>art. no.</b>  <b>ICK BGA 14 x 14 x 10</b> WLF ... 14 x 14		
<b>art. no.</b>  <b>ICK BGA 21 x 21</b> WLF ... 21 x 21		

Thermal conduct. foil WLFT 404/405 → E ?  
 Thermal conductive glue → E ?  
 Thermal conductive paste → E ?  
 Processor overview → B 2 - 7

SMD-heatsinks → B ? - ?  
 Mounting material for semiconduct. → E ? - ?  
 Hole pattern → A 21  
 Technical introduction → A 2 - 7

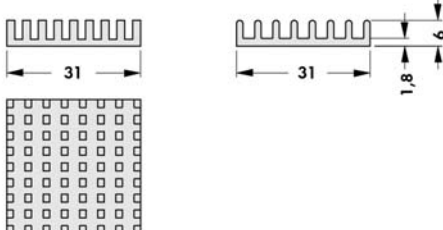
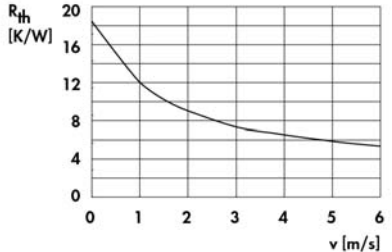
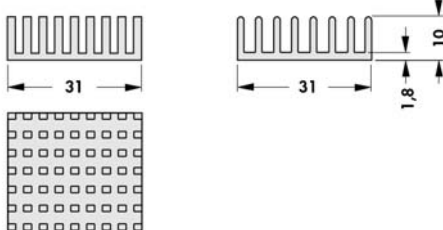
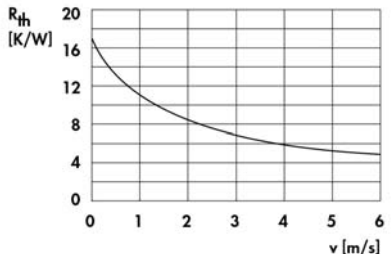
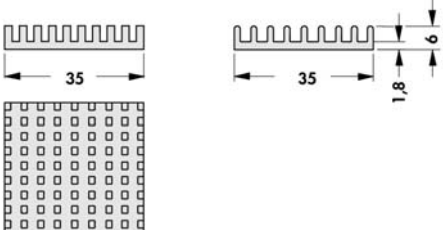
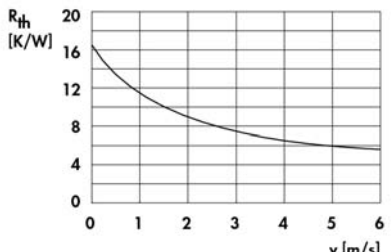
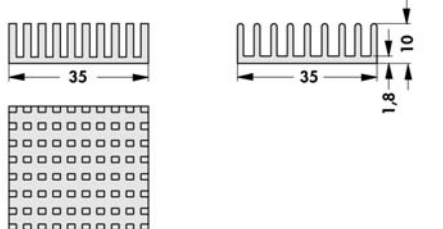
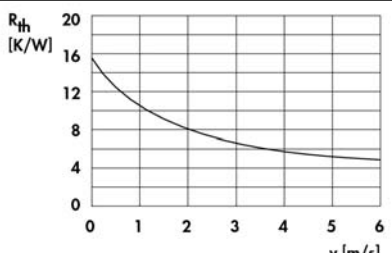
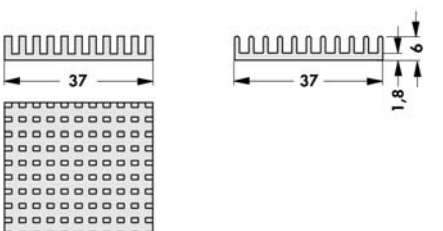
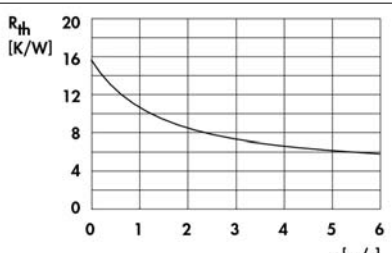
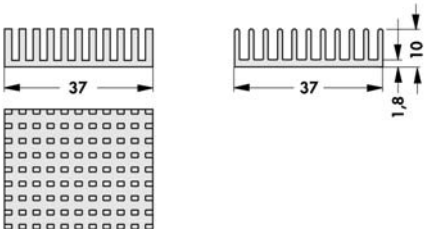
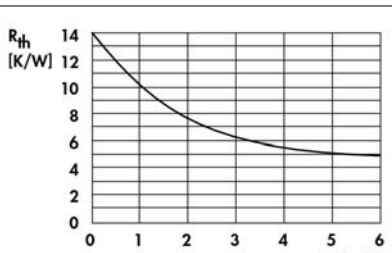
## Heatsinks for BGAs

<p><b>art. no.</b></p> <p><b>ICK BGA 23 x 23</b> WLF ... 23 x 23</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 23 x 23 x 10</b> WLF ... 23 x 23</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 27 x 27</b> WLF ... 27 x 27</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 27 x 27 x 10</b> WLF ... 27 x 27</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 27 x 27 x 14</b> WLF ... 27 x 27</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 27 x 27 x 22</b> WLF ... 27 x 27</p>		

Thermal conduct. foil WLFT 404/405 → E ?  
 Thermal conductive glue → E ?  
 Thermal conductive paste → E ?  
 Processor overview → B 2 - 7

SMD-heatsinks → B ? - ?  
 Mounting material for semiconduct. → E ? - ?  
 Hole pattern → A 21  
 Technical introduction → A 2 - 7

## Heatsinks for BGAs

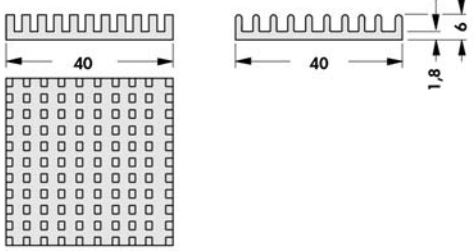
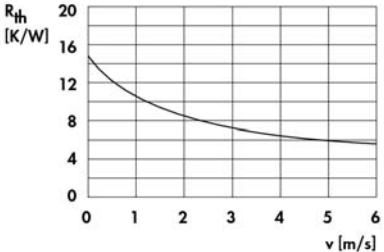
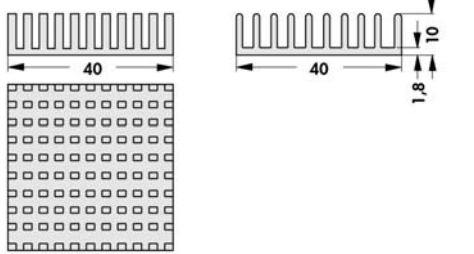
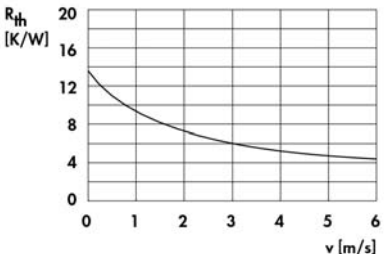
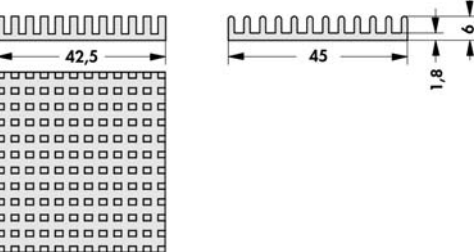
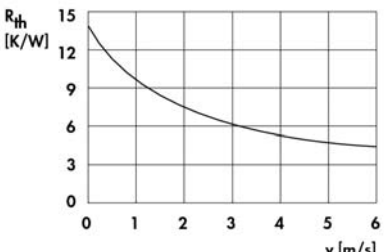
<p><b>art. no.</b></p> <p><b>ICK BGA 31 x 31</b> WLF ... 31 x 31</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 31 x 31 x 10</b> WLF ... 31 x 31</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 35 x 35</b> WLF ... 35 x 35</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 35 x 35 x 10</b> WLF ... 35 x 35</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 37 x 37 x 6</b> WLF ... 37 x 37</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 37 x 37 x 10</b> WLF ... 37 x 37</p>		

**B 5**

Thermal conduct. foil WLFT 404/405 → E ?  
 Thermal conductive glue → E ?  
 Thermal conductive paste → E ?  
 Processor overview → B 2 - 7

SMD-heatsinks → B ? - ?  
 Mounting material for semiconduct. → E ? - ?  
 Hole pattern → A 21  
 Technical introduction → A 2 - 7

## Heatsinks for BGAs

<p><b>art. no.</b></p> <p><b>ICK BGA 40 x 40</b> WLF ... 40 x 40</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 40 x 40 x 10</b> WLF ... 40 x 40</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 42,5 x 45</b> WLF ... 42,5 x 45</p>		

A

B

C

D

E

F

G

H

I

K

L

M

Thermal conduct. foil WLFT 404/405 → E ?  
 Thermal conductive glue → E ?  
 Thermal conductive paste → E ?  
 Processor overview → B 2 - 7

SMD-heatsinks → B ? - ?  
 Mounting material for semiconduct. → E ? - ?  
 Hole pattern → A 21  
 Technical introduction → A 2 - 7

N